221 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
222 These assemblies are ESD sensitive, ESD precautions shall be observed.
223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
224 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE  BOARD #: PMP9393  REV: 1B  SUN REV: Not In VersionControl
IGNORE -> Top Overlay

PLOT NAME = Top Assembly Drawing  GENERATED: 3/24/2015 3:56:53 PM  TEXAS INSTRUMENTS
COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP9393</th>
<th>REV: 1B</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>IGNORE</td>
<td></td>
<td>Bottom Overlaid</td>
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PLOT NAME = Bottom Assembly Drawing
GENERATED : 3/24/2015 3:56:54 PM
TEXAS INSTRUMENTS
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